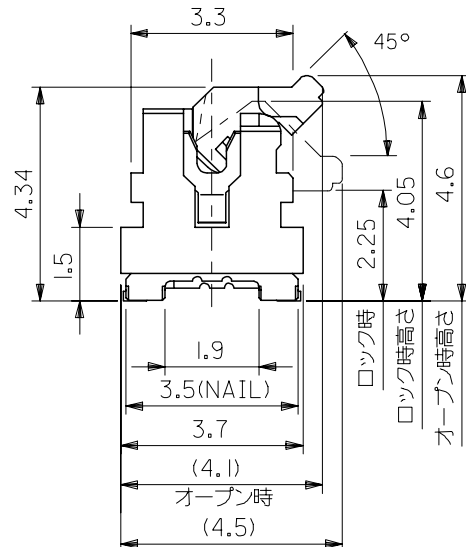
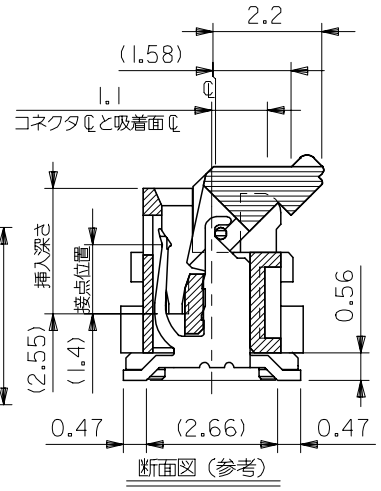
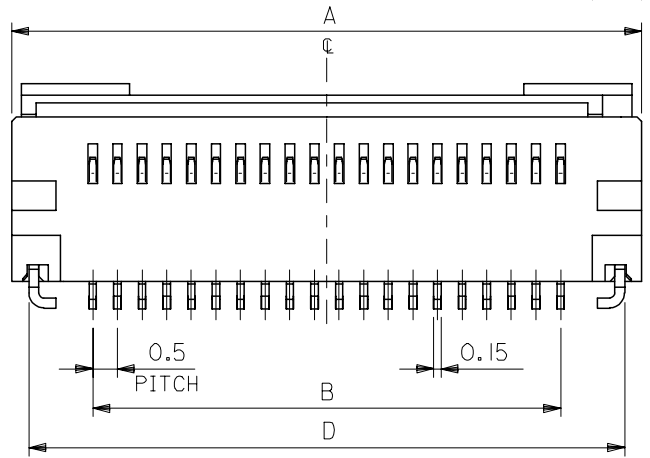
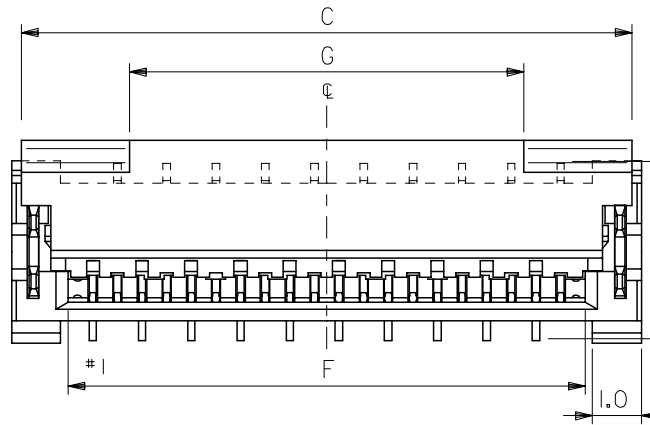


10 9 8 7 6 5 4 3 2 1



注記  
NOTES:

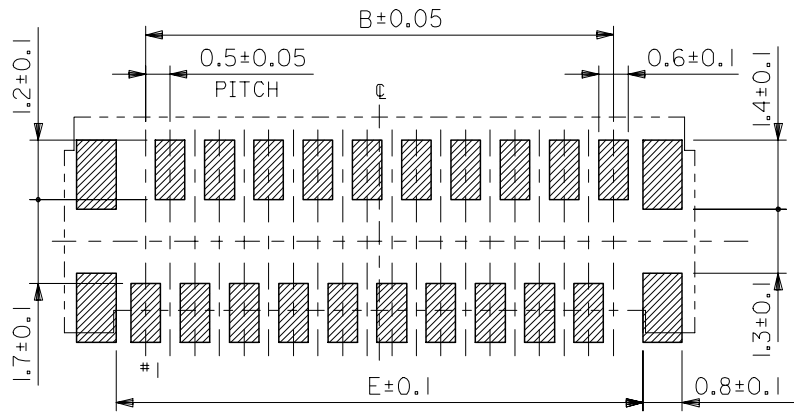
1. 材質  
MATERIAL  
ハウジング: LCP (液晶ポリマー)、ガラス充填、白色、UL94V-0  
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, WHITE, UL94V-0  
アクチュエータ: PPS、ガラス充填、茶色、UL94V-0  
ACTUATOR: PPS (POLYPHENYLENE SULFIDE), GLASS FILLED, BROWN, UL94V-0  
ターミナル: 銅合金 (t=0.15)  
TERMINAL: COPPER ALLOY (t=0.15)  
金具: 銅合金 (t=0.2)  
NAIL: COPPER ALLOY (t=0.2)
2. メッキ仕様  
PLATING  
ターミナル  
TERMINAL  
接点部: 金メッキ 0.1μm 以上  
CONTACT AREA: Au PLATING 0.1 MICROMETER MINIMUM.  
テール部: 錫メッキ 1.0μm 以上  
TAIL AREA: TIN PLATING 1.0 MICROMETER MINIMUM.  
下地メッキ: ニッケルメッキ 1.0μm 以上  
UNDER PLATING: NICKEL PLATING 1.0 MICROMETER MINIMUM.
3. テールと金具を併せた平坦度は、0.1ミリアール以下。  
TAILS AND NAILS COPLANARITY TO BE 0.1 MICROMETER MAXIMUM.

8	30.5	30.7	32.1	32.4	29.5	32.8	51374-6028	60
8	25.5	25.7	27.1	27.4	24.5	27.8	51374-5028	50
8	23.0	23.2	24.6	24.9	22.0	25.3	51374-4528	45
8	20.5	20.7	22.1	22.4	19.5	22.8	51374-4028	40
8	15.5	15.7	17.1	17.4	14.5	17.8	51374-3028	30
8	12.5	12.7	14.1	14.4	11.5	14.8	51374-2428	24
4.5	5.5	5.7	7.1	7.4	4.5	7.8	51374-1028	10
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

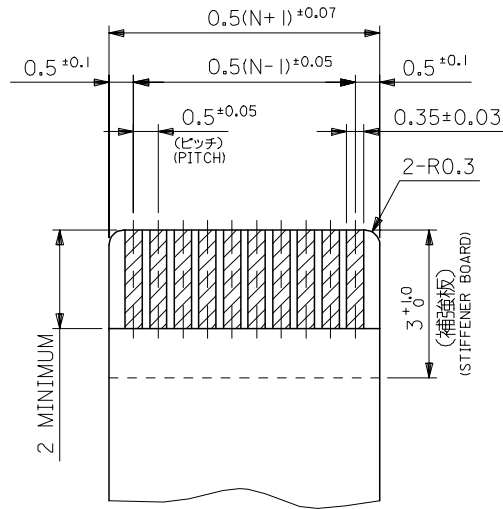
REVISED EC NO: J2006-2397 DRW: NAIDA CHK: KTOYODA APP: NUKITA	DESCRIPTION 2006/01/27 2006/01/31 2006/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY M. NABEI	DATE '05/07/15	TITLE 0.5 FPC CONN. HS'G ASS'Y EASY ON / STRAIGHT -LEAD FREE-  MOLEX INCORPORATED			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE '05/07/15				
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE '05/07/15				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-51374-026		SHEET NO. 1 OF 2	

10 9 8 7 6 5 4 3 2 1

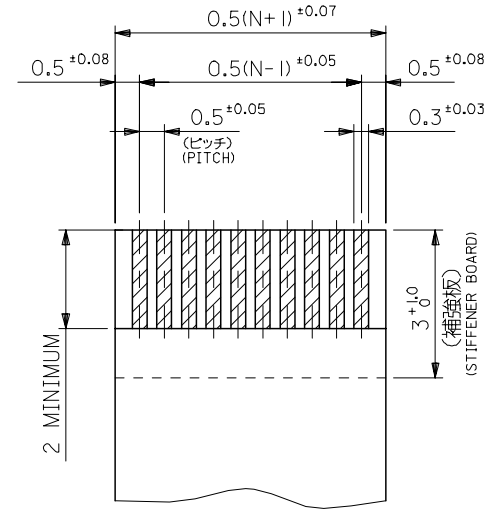
F  
E  
D  
C  
B  
A



参考基板レイアウト (マウント面)  
P.C. BOARD PATTERN DIMENSION (REF.)  
(MOUNT AREA)



適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.3 ± 0.05)  
(THICKNESS: 0.3 ± 0.05)



適合FFC推奨寸法  
APPLICABLE FFC  
RECOMMENDED DIMENSION  
(仕上がり厚さ: 0.3 ± 0.05)  
(THICKNESS: 0.3 ± 0.05)

N: 極数  
N: CIRCUITS

N: 極数  
N: CIRCUITS

FPC/FFCについて:

打抜き方向は導体側から補強板側を推奨いたします。  
導体部については軟銅箔35マイクロメートルまたは50マイクロメートル

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPEC :  
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER

FPCについて:

補強フィルム材質はポリイミドを推奨します。  
接着剤は熱硬化接着剤を推奨します。

ABOUT FPC

RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2006-2397 DRW:NAIDA 2006/01/27 CHK:KTOYODA 2006/01/31 APPR:NUKITA 2006/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± 0.2	DRAWN BY M. NABEI	DATE '05/07/15	TITLE 0.5 FPC CONN. HS'G ASS'Y EASY ON / STRAIGHT -LEAD FREE-			
	10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOYODA	DATE '05/07/15				
	30 OVER	± 0.3	APPROVED BY N. UKITA	DATE '05/07/15	MOLEX INCORPORATED			
	ANGULAR	± 3 °	MATERIAL NO.	DOCUMENT NO. SD-51374-026				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				